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January 2009

FDD8444L_F085

N-Channel PowerTrench[®] MOSFET

40V, **50A**, **6.0m** Ω

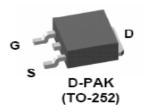
Features

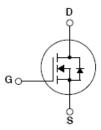
- Typ $r_{DS(on)}$ = 3.8m Ω at V_{GS} = 5V, I_D = 50A
- Typ $Q_{g(tot)}$ = 46nC at V_{GS} = 5V
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse/ Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant



Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Transmission
- Distributed Power Architecture and VRMs
- Primary Switch for 12V and 24V systems





MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		40	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current Continuous (T _C < 150°C, V _{GS} = 10V)	(Note 1)	50	
I_D	Continuous ($T_{amb} = 25^{\circ}C$, $V_{GS} = 10V$, with $R_{\theta JA} = 52^{\circ}C/W$)		16	Α
	Pulsed		See Figure 4	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	295	mJ
П	Power Dissipation		153	W
P_{D}	Derate above 25°C		1.02	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.98	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252, 1in ² copper pad area	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8444L	FDD8444L_F085	TO-252AA	13"	12mm	2500 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Cha	Off Characteristics						

B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		40	-		V
		$V_{DS} = 32V$,				1	^
DSS	I _{DSS} Zero Gate Voltage Drain Current	$V_{GS} = 0V$	$T_{J} = 150^{\circ}C$	-	-	250	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1	1.8	3	V
		I _D = 50A, V _{GS} = 10V	-	3.5	5.2	
		I _D = 50A, V _{GS} = 5V	-	3.8	6.0	
r _{DS(on)}	Drain to Source On Resistance	I _D = 50A, V _{GS} = 4.5V	-	4.0	6.5	mΩ
		I _D = 50A, V _{GS} = 5V, T _J = 175°C	-	6.8	10.7	

Dynamic Characteristics

C _{iss}	Input Capacitance	\/ - 25\/ \/ - 0	N. /	-	5530	-	pF
Coss	Output Capacitance	V _{DS} = 25V, V _{GS} = 0 f = 1MHz	JV,	-	605	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112		-	400	-	pF
R_G	Gate Resistance	f = 1MHz		-	1.7		Ω
$Q_{g(TOT)}$	Total Gate Charge at 5V	$V_{GS} = 0$ to 5V		-	46	60	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	V _{DD} = 20V	-	5.4	7	nC
Q_{gs}	Gate to Source Gate Charge	I _D = 50A		-	16.3		nC
Q _{gs2}	Gate Charge Threshold to Plateau	I _g = 1.0mA		-	10.9	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	21	-	nC

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Switching Characteristics

t _{on}	Turn-On Time		-	-	104	ns
t _{d(on)}	Turn-On Delay Time		1	18.7	-	ns
t _r	Turn-On Rise Time	$V_{DD} = 20V, I_{D} = 50A$ $V_{GS} = 5V, R_{GS} = 2\Omega$	1	46	-	ns
$t_{d(off)}$	Turn-Off Delay Time	VGS - 3V, NGS - 212	1	42	-	ns
t _f	Turn-Off Fall Time		1	19.2	-	ns
t_{off}	Turn-Off Time		1	-	96	ns

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Voltage	I _{SD} = 50A	-	0.9	1.25	V	
V_{SD}	Source to Drain Diode Voltage	I _{SD} = 25A	-	0.8	1.0	V
t _{rr}	Reverse Recovery Time			34	44	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 50A$, $dI_F/dt = 100A/\mu s$	-	29	38	nC

Package current limitation is 50A.
 Starting T_J = 25°C, L = 0.37mH, I_{AS} = 40A.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

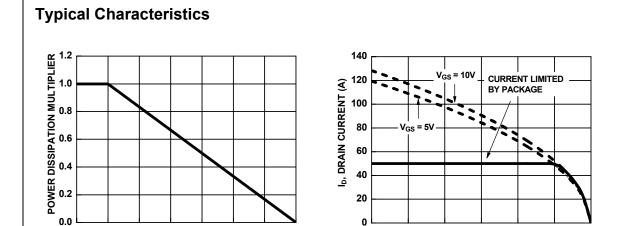


Figure 1. Normalized Power Dissipation vs Case Temperature

T_C, CASE TEMPERATURE(°C)

100

0

25

Figure 2. Maximum Continuous Drain Current vs Case Temperature

100

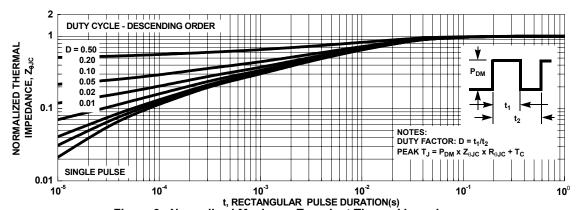
T_C, CASE TEMPERATURE(°C)

125

150

175

75



25

50

Figure 3. Normalized Maximum Transient Thermal Impedance

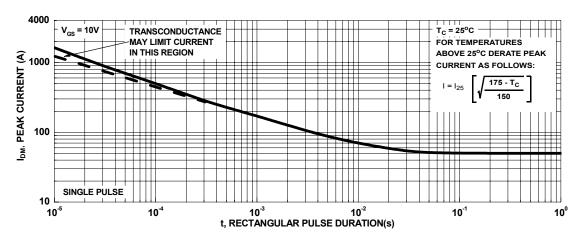


Figure 4. Peak Current Capability

Typical Characteristics

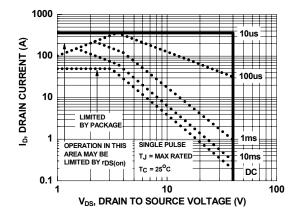
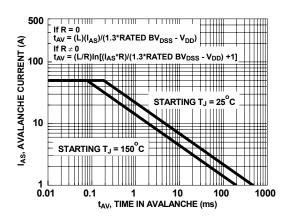


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

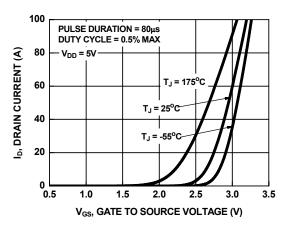


Figure 7. Transfer Characteristics

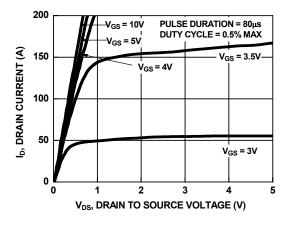


Figure 8. Saturation Characteristics

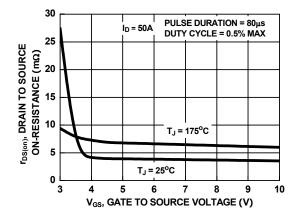


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

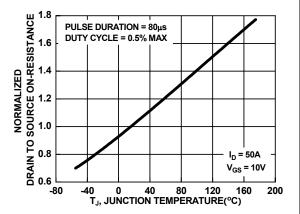


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

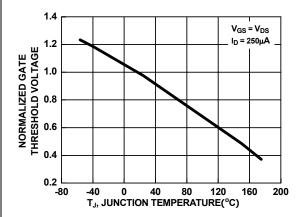


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

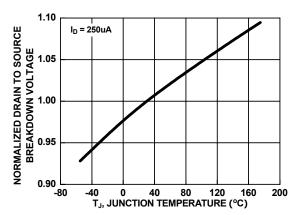


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

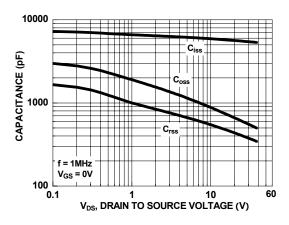


Figure 13. Capacitance vs Drain to Source Voltage

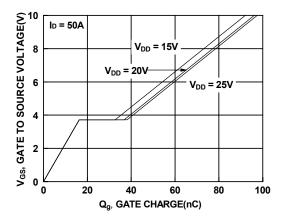


Figure 14. Gate Charge vs Gate to Source Voltage





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